

1. Global joint venture starts operations as WeEn Semiconductors

Dear customer.

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

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Thank you for your cooperation and understanding,

WeEn Semiconductors



DISCRETE SEMICONDUCTORS

DATA SHEET

BYV44 seriesDual rectifier diodes ultrafast

Product specification

October 1998



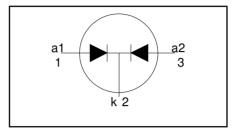
Dual rectifier diodes ultrafast

BYV44 series

FEATURES

- · Low forward volt drop
- · Fast switching
- · Soft recovery characteristic
- High thermal cycling performance
- · Low thermal resistance

SYMBOL



QUICK REFERENCE DATA

$$V_R = 300 \text{ V} / 400 \text{ V} / 500 \text{ V}$$
 $V_F \le 1.12 \text{ V}$
 $I_{O(AV)} = 30 \text{ A}$
 $t_{rr} \le 60 \text{ ns}$

GENERAL DESCRIPTION

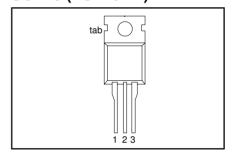
Dual, common cathode, ultra-fast, epitaxial rectifier diodes intended for use as output rectifiers in high frequency switched mode power supplies.

The BYV44 series is supplied in the conventional leaded SOT78 (TO220AB) package.

PINNING

PIN	DESCRIPTION		
1	anode 1		
2	cathode		
3	anode 2		
tab	cathode		

SOT78 (TO220AB)



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.			UNIT
V _{RRM} V _{RWM} V _R	Peak repetitive reverse voltage Crest working reverse voltage Continuous reverse voltage	$\textbf{BYV44}$ $T_{mb} \leq 136 ^{\circ} \text{C}$	- - -	-300 300 300 300	-400 400 400 400	-500 500 500 500	V V V
I _{O(AV)}	(both diodes conducting) ¹	square wave; $\delta = 0.5$; $T_{mb} \le 94 ^{\circ}C$	-		30		Α
I _{FRM}	Repetitive peak forward current per diode Non-repetitive peak forward	$T_{mb} \le 94 ^{\circ}C$ t = 10 ms	-		30 150		A
	current per diode.		-		160		A
T _{stg}	Storage temperature Operating junction temperature	Trini(max)	-40 -		150 150		.C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th j-hs}$ $R_{th j-a}$	heatsink	per diode both diodes conducting in free air.		- - 60	2.4 1.4 -	K/W K/W K/W

¹ Neglecting switching and reverse current losses.

For output currents in excess of 20 A, the cathode connection should be made to the metal mounting tab.

NXP Semiconductors Product specification

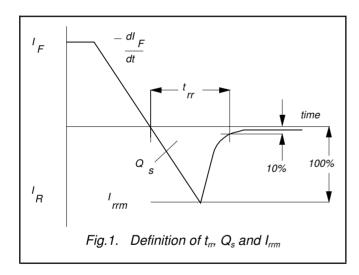
Dual rectifier diodes ultrafast

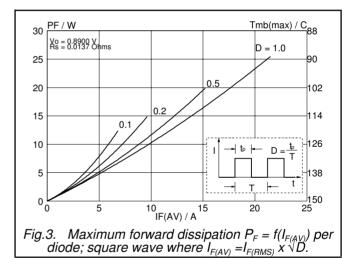
BYV44 series

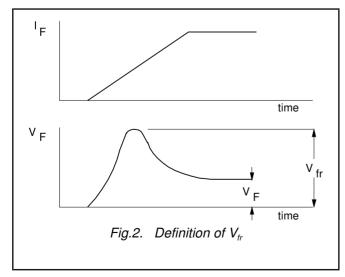
ELECTRICAL CHARACTERISTICS

characteristics are per diode at T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _F	Forward voltage	$I_{\rm F} = 15 \text{ A}; T_{\rm i} = 150 ^{\circ}\text{C}$	-	0.95	1.12	V
		$I_{\rm F} = 15 {\rm A}$	-	1.08	1.25	V
		$I_{\rm F} = 30 \text{ A}$	-	1.15	1.36	V
I _R	Reverse current	$V_R = V_{RRM}$	-	10	50	μΑ
		$V_{R} = V_{RRM}^{(NRM)}; T_{j} = 100 ^{\circ}C$ $I_{F} = 2 ^{\circ}A ^{\circ}to V_{R} \geq 30 ^{\circ}V;$	-	0.3	0.8	mΑ
$Q_{\rm s}$	Reverse recovery charge	$I_F = 2 \text{ Å to } V_B \ge 30 \text{ V};$	-	40	60	nC
		$dI_{F}/dt = 20 A/\mu s$				
t _{rr}	Reverse recovery time	$I_F = 1 \text{ A to } V_R \ge 30 \text{ V};$	-	50	60	ns
	-	$dI_F/dt = 100 A/\mu s$				
I _{rrm}	Peak reverse recovery current	$I_{\rm F} = 10 \text{ A to } V_{\rm B} \ge 30 \text{ V};$	-	4.2	5.2	Α
	,	$I_F = 10 \text{ A to } V_R \ge 30 \text{ V};$ $dI_F/dt = 50 \text{ A/}\mu\text{s}; T_i = 100^{\circ}\text{C}$				
V_{fr}	Forward recovery voltage	$I_F = 10 \text{ A}$; $dI_F/dt = 10 \text{ A}/\mu\text{s}$	-	2.5	-	V







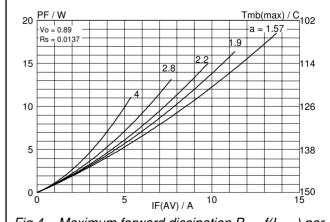
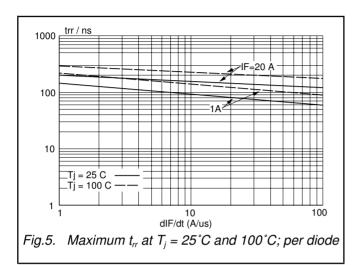


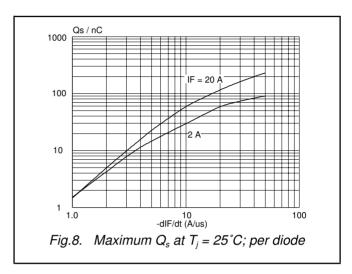
Fig.4. Maximum forward dissipation $P_F = f(I_{F(AV)})$ per diode; sinusoidal current waveform where a = form factor $= I_{F(RMS)} / I_{F(AV)}$.

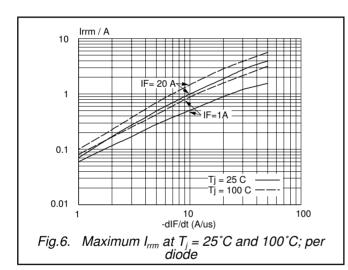
NXP Semiconductors Product specification

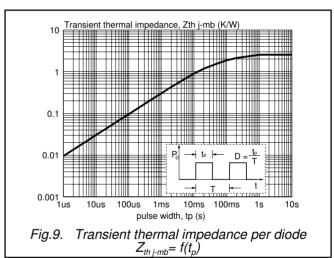
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BYV44 series









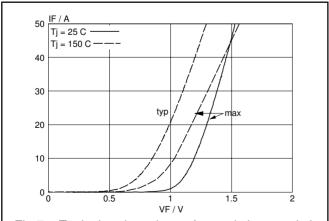


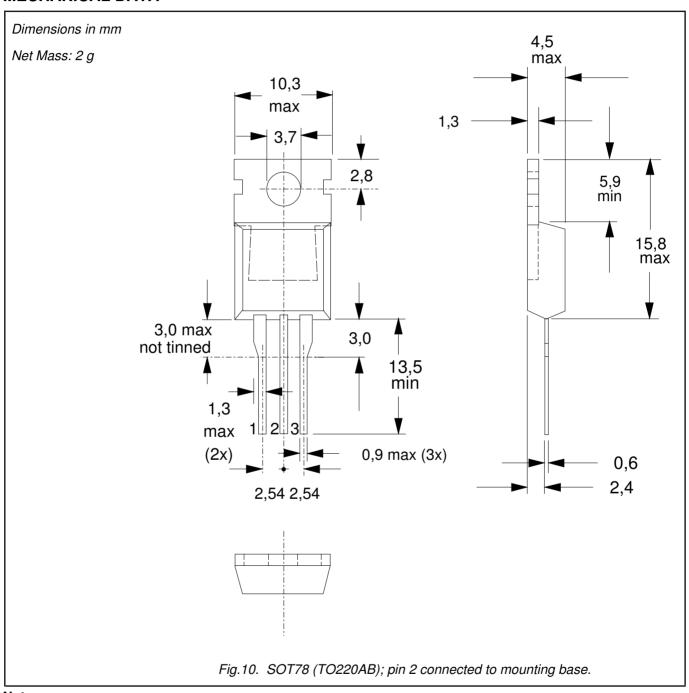
Fig.7. Typical and maximum forward characteristic $I_F = f(V_F)$; parameter T_i

NXP Semiconductors Product specification

Dual rectifier diodes ultrafast

BYV44 series

MECHANICAL DATA



- Notes
 1. Refer to mounting instructions for SOT78 (TO220) envelopes.
 2. Epoxy meets UL94 V0 at 1/8".

Legal information

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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